

**P-Channel MOSFET** 

## **General Description**

The WSD30L90DN56 is the highest performance trench P-Channel MOSFET with extreme high cell density, which provide excellent  $R_{DS(ON)}$  and gate charge for most of the synchronous buck converter applications.

The WSD30L90DN56 meet the RoHS and Green Product requirement 100%  $E_{AS}$  guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% E<sub>AS</sub> Guaranteed
- Green Device Available

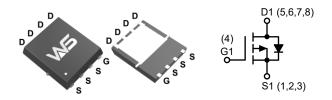
## **Product Summery**

| BV <sub>DSS</sub> | R <sub>DS(ON)</sub> | I <sub>D</sub> |
|-------------------|---------------------|----------------|
| -30V              | 5.2mΩ               | -90A           |

## **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

## **DFN5X6-8L Pin Configuration**



# **Absolute Maximum Ratings**

| Complete  | Double of the state of the stat | Rat        | Unito        |       |  |
|---|--|------------|--------------|-------|--|
| Symbol  | Parameter  | 10s        | Steady State | Units |  |
| V <sub>DS</sub> Drain-Source Voltage                                |  | -30        |              | V     |  |
| $V_{GS}$  | Gate-Source Voltage  | ±25        |              | V     |  |
| I <sub>D</sub> @T <sub>C</sub> =25°C                                | Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>  | -9         | 90           |       |  |
| I <sub>D</sub> @T <sub>C</sub> =100°C                               | Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>  | -5         | -57          |       |  |
| I <sub>D</sub> @T <sub>A</sub> =25°C                                | I <sub>D</sub> @T <sub>A</sub> =25°C Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>   |            | -22          | Α     |  |
| I <sub>D</sub> @T <sub>A</sub> =70°C                                | °C Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup> -24   |            | -19          |       |  |
| I <sub>DM</sub>   | Pulsed Drain Current <sup>2</sup>  |            | -360         |       |  |
| E <sub>AS</sub>   | Single Pulse Avalanche Energy <sup>3</sup>   | 88         |              | mJ    |  |
| I <sub>AS</sub>   | Avalanche Current  | -42        |              | Α     |  |
| P <sub>D</sub> @T <sub>C</sub> =25°C Power Dissipation <sup>4</sup> |  | 40         |              | W     |  |
| P <sub>D</sub> @T <sub>A</sub> =25°C                                | P <sub>D</sub> @T <sub>A</sub> =25°C Power Dissipation <sup>4</sup>  |            | 6.15         | V V   |  |
| T <sub>STG</sub>  | Storage Temperature Range -55 to 150   |            | o 150        | °C    |  |
| T <sub>J</sub> Operating Junction Temperature Range                 |  | -55 to 150 |              |       |  |

### **Thermal Data**

| Symbol         | Parameter  | Тур. | Max. | Units |
|----------------|--|------|------|-------|
| $R_{	heta JA}$ | Thermal Resistance, Junction-to-Ambient <sup>1</sup>           |      | 50   |       |
| $R_{	heta JA}$ | Thermal Resistance, Junction-to-Ambient <sup>1</sup> ( t ≤10s) |      | 20   | °C/W  |
| $R_{	heta JC}$ | Thermal Resistance, Junction-to-Case <sup>1</sup>              |      | 1.6  |       |

**P-Channel MOSFET** 

# **Electrical Characteristics** (T<sub>J</sub>=25°C, Unless Otherwise Noted)

| Symbol                         | Parameter                                      | Conditions   | Min. | Тур.    | Max. | Units |
|--------------------------------|--|--|------|---------|------|-------|
| BV <sub>DSS</sub>              | Drain-Source Breakdown Voltage                 | V <sub>GS</sub> =0V , I <sub>D</sub> =-250μA   | -30  |         |      | V     |
| $\Delta BV_{DSS}/\Delta T_{J}$ | BV <sub>DSS</sub> Temperature Coefficient      | Reference to 25°C, I <sub>D</sub> =-1mA  |      | -0.0332 |      | V/°C  |
| В                              | Static Project Source On Registers 2           | V <sub>GS</sub> =-10V , I <sub>D</sub> =-25A   |      | 5.2     | 6.4  |       |
| $R_{DS(ON)}$                   | Static Drain-Source On-Resistance <sup>2</sup> | V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-10A  |      | 8.6     | 12   | mΩ    |
| $V_{GS(th)}$                   | Gate Threshold Voltage                         | \\ -\\     - 250\  | -1.3 | -1.8    | -2.3 | V     |
| $\Delta V_{GS(th)}$            | V <sub>GS(th)</sub> Temperature Coefficient    | $V_{GS}=V_{DS}$ , $I_{D}=-250\mu$ A  |      | 4.4     |      | mV/°C |
|                                | Zara Cata Valtaga Drain Current                | V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C                           |      |         | 1.0  | μA    |
| I <sub>DSS</sub>               | Zero Gate Voltage Drain Current                | V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C                           |      |         | 5.0  |       |
| I <sub>GSS</sub>               | Gate-Body Leakage Current                      | $V_{GS}$ =±20V , $V_{DS}$ =0V  |      |         | ±100 | nA    |
| 9 <sub>fs</sub>                | Forward Transconductance                       | V <sub>DS</sub> =-5V , I <sub>D</sub> =-30A  |      | 28      |      | S     |
| $R_g$                          | Gate Resistance                                | $V_{DS}$ =0V , $V_{GS}$ =0V , f = 1.0MHz   |      | 2.0     | 5.0  | Ω     |
| $Q_g$                          | Total Gate Charge(-4.5)                        | V <sub>DS</sub> =-15V , V <sub>GS</sub> =-10V ,<br>I <sub>D</sub> =-25A                      |      | 70      |      |       |
| $Q_gs$                         | Gate-Source Charge                             |  |      | 10      |      | nC    |
| $Q_gd$                         | Gate-Drain Charge                              | 0 _20/1  |      | 18      |      |       |
| T <sub>d(on)</sub>             | Turn-On Delay Time                             | $V_{DD}$ =-15V , $V_{GEN}$ =-10V , $R_{G}$ =6 $\Omega$ , $I_{D}$ =-1A , $R_{L}$ =15 $\Omega$ |      | 15      |      |       |
| T <sub>r</sub>                 | Rise Time                                      |  |      | 19      |      | no.   |
| T <sub>d(off)</sub>            | Turn-Off Delay Time                            |  |      | 88      |      | ns    |
| T <sub>f</sub>                 | Fall Time                                      |  |      | 62      |      |       |
| C <sub>iss</sub>               | Input Capacitance                              | V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , f = 1.0MHz                                     |      | 3200    |      |       |
| C <sub>oss</sub>               | Output Capacitance                             |  |      | 640     |      | pF    |
| C <sub>rss</sub>               | Reverse Transfer Capacitance                   |  |      | 600     |      |       |

### **Guaranteed Avalanche Characteristics**

| Symbol          | Parameter                                  | Conditions  | Min. | Тур. | Max. | Units |
|-----------------|--|---|------|------|------|-------|
| E <sub>AS</sub> | Single Pulse Avalanche Energy <sup>5</sup> | V <sub>DD</sub> =-25V , L=0.5mH , I <sub>AS</sub> =-36A | 88   |      |      | mJ    |

## **Diode Characteristics**

| Symbol          | Parameter                            | Conditions   | Min. | Тур. | Max. | Units |
|-----------------|--------------------------------------|--|------|------|------|-------|
| I <sub>S</sub>  | Continuous Source Current 1,6        | V <sub>G</sub> =V <sub>D</sub> =0V , Force Current               |      |      | -45  | ^     |
| I <sub>SM</sub> | Pulsed Source Current <sup>2,6</sup> |  |      |      | -300 | A     |
| $V_{SD}$        | Diode Forward Voltage <sup>2</sup>   | V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25°C |      |      | -1.0 | V     |
| t <sub>rr</sub> | Reverse Recovery Time                | I <sub>F</sub> =-15A,dI/dt=100A/μs,T <sub>J</sub> =25°C          |      | 30   |      | ns    |
| Q <sub>rr</sub> | Reverse Recovery Charge              |  |      | 14   |      | nC    |

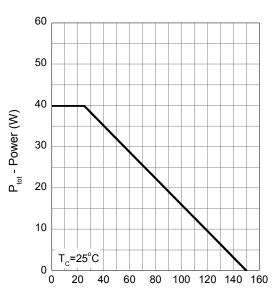
#### Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t≤10sec.
- 2. The data tested by pulsed , pulse width  $\leq 300 \mu s$  , duty cycle  $\leq 2\%$
- 3. The E $_{AS}$  data shows Max. rating . The test condition is  $V_{DD}$ =-25V,  $V_{GS}$ =-10V, L=0.5mH, I $_{AS}$ =-36A
- 4. The power dissipation is limited by 150°C junction temperature.
- 5. The Min. value is 100% E<sub>AS</sub> tested guarantee.
- 6. The data is theoretically the same as  $\ensuremath{I_D}$  and  $\ensuremath{I_{DM}}$  , in real applications , should be limited by total power dissipation.



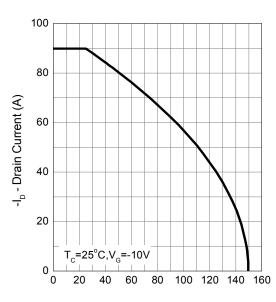
# **Typical Characteristics**

**Power Dissipation** 



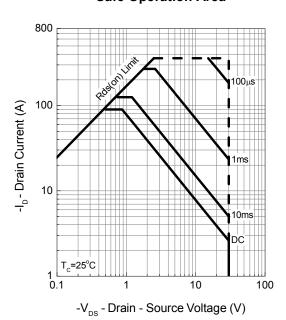
T<sub>i</sub> - Junction Temperature (°C)

#### **Drain Current**

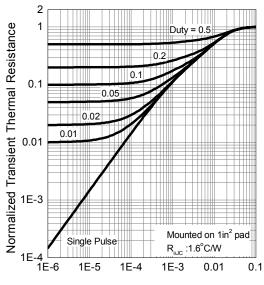


T<sub>i</sub> - Junction Temperature (°C)

## **Safe Operation Area**



## **Thermal Transient Impedance**

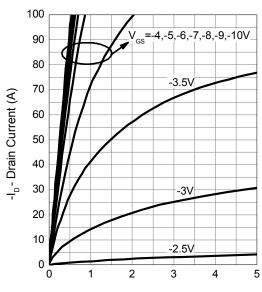


Square Wave Pulse Duration (sec)



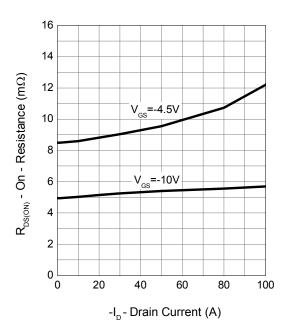
# **Typical Characteristics (Cont.)**

# **Output Characteristics**

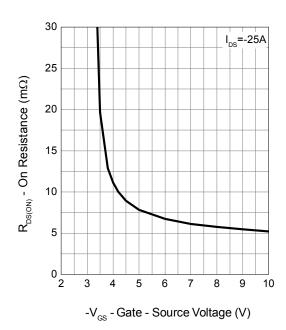


-V<sub>DS</sub> - Drain-Source Voltage (V)

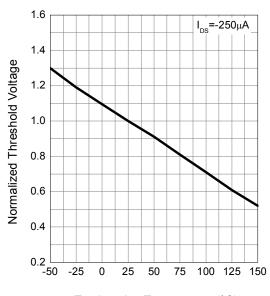
#### **Drain-Source On Resistance**



### **Gate-Source On Resistance**



## **Gate Threshold Voltage**

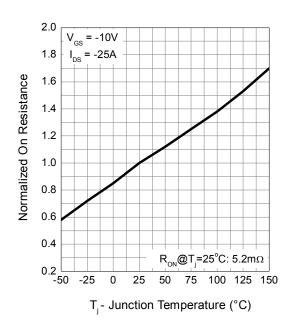


T<sub>i</sub> - Junction Temperature (°C)

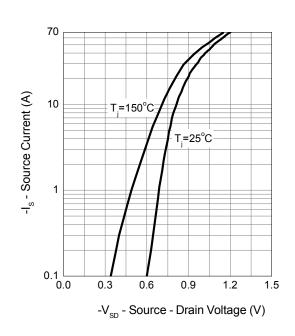


# **Typical Characteristics (Cont.)**

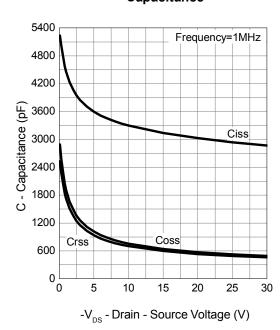
#### **Drain-Source On Resistance**



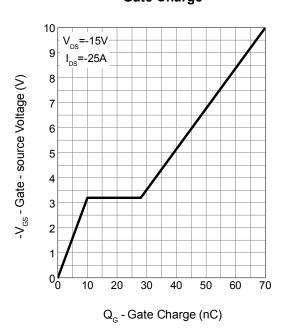
#### Source-Drain Diode Forward



### Capacitance



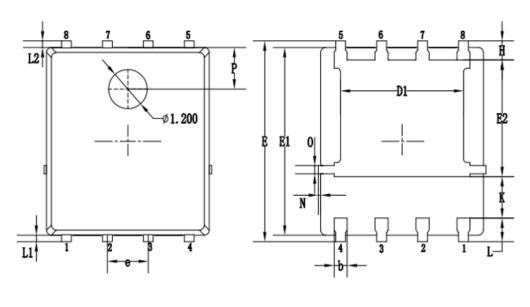
## **Gate Charge**

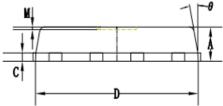




**P-Channel MOSFET** 

# **Packaging information**





| SYMBOLS | MILLIMETERS |           |      |  |  |  |
|---------|-------------|-----------|------|--|--|--|
|         | MIN.        | NOM.      | MAX. |  |  |  |
| Α       | 0.90        | 1.05      | 1.20 |  |  |  |
| b       | 0.35        | 0.40      | 0.50 |  |  |  |
| С       | 0.20        | 0.25      | 0.35 |  |  |  |
| D       | 4.90        | 5.05      | 5.20 |  |  |  |
| D1      | 3.72        | 3.82      | 3.92 |  |  |  |
| E       | 6.00        | 6.15      | 6.30 |  |  |  |
| E1      | 5.60        | 5.75      | 5.90 |  |  |  |
| E2      | 3.47        | 3.57      | 3.67 |  |  |  |
| е       |             | 1.27 BSC. |      |  |  |  |
| Н       | 0.48        | 0.58      | 0.68 |  |  |  |
| K       | 1.17        | 1.27      | 1.37 |  |  |  |
| L       | 0.64        | 0.74      | 0.84 |  |  |  |
| L1/L2   |             | 0.20 REF. |      |  |  |  |
| θ       | 8°          | 10°       | 12°  |  |  |  |
| М       |             | 0.08 REF. |      |  |  |  |
| N       | 0           | -         | 0.15 |  |  |  |
| 0       |             | 0.25 REF. |      |  |  |  |
| Р       |             | 1.28 REF. |      |  |  |  |



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